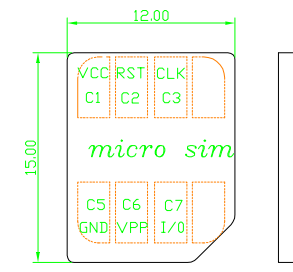
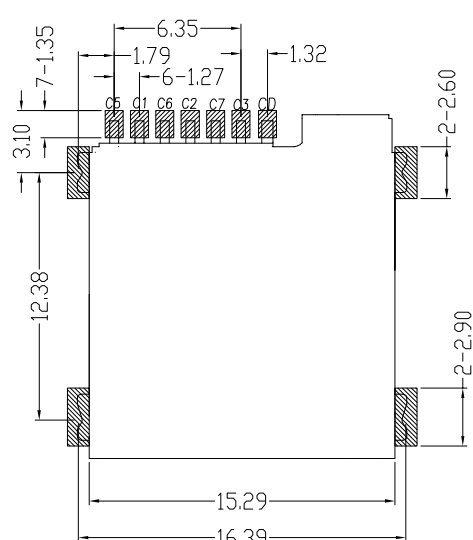
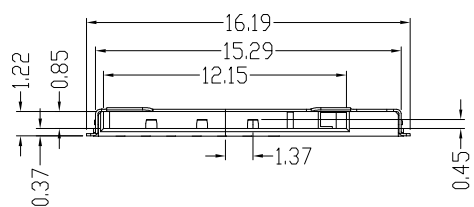
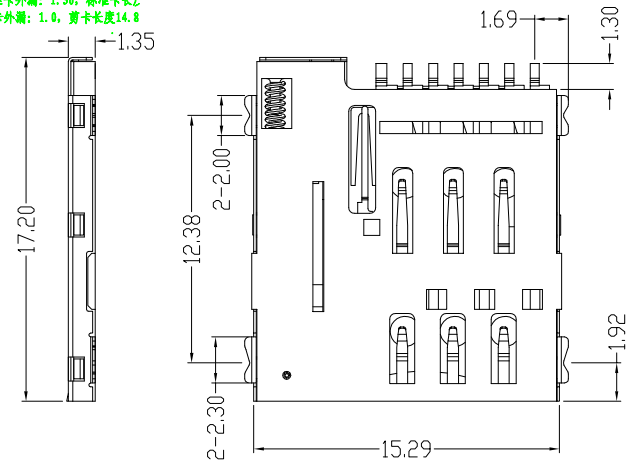
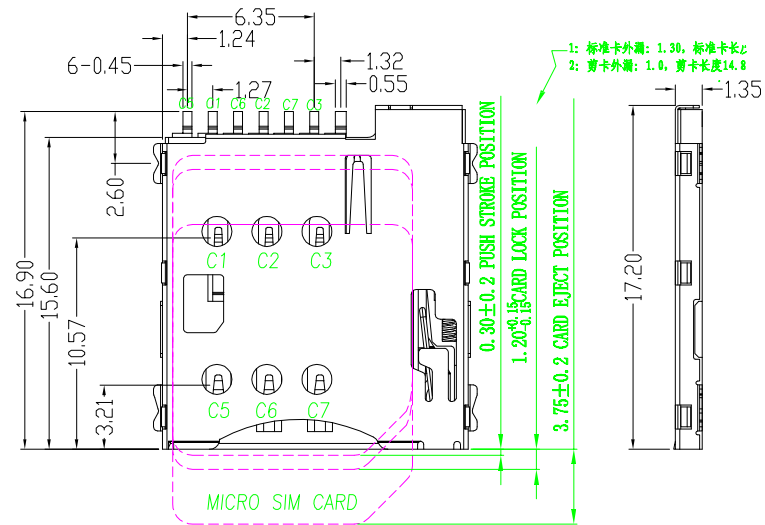


| 修 订 | 标 记 | 修 改 描 要 | 签 名 | 日 期 |
|-----|------|----------------------|-----------|------------|
| REV | MARK | REVISION DESCRIPTION | SIGNATURE | DATE |
| AO | | NEW DWG | | 2016-03-12 |



MICRO SIM CARD

PCB 焊盘区
下沉位区

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

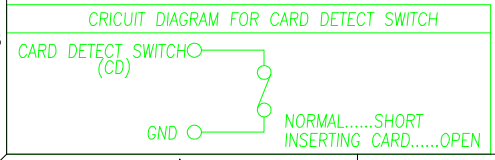
Specification

MATERIAL:
Insulator: High Temperature Thermoplastic, UL 94V-0,
Contact: Copper Alloy
SHELL: SUS

PLATING:
Contact: Plated 50u' Ni Overall Contact Au 1U
Shell: Plated 50u' Ni Overall
Plated 1u'Au Selective Contact Area

Electrical:
Current Rating :0.5mA AC/DC max.
Voltage Rating :125V AC/DC
Ambient Temperature Range :-20° C~+60° C
Storage Temperature Range :-40° C~+70° C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100M max. Ω
Insulation Resistance:1000M min./500VDC
产品耐温温度: 260° C - C 84.70 - C 84.70 ± 5 C
Mating Cycles:3000Min Insertions

| SIM pin assignment | |
|--------------------|---------|
| PIN# | Name |
| C1 | VCC供电电压 |
| C2 | RST重置 |
| C3 | CLK时钟 |
| C5 | GND接地 |
| C6 | VPP程序电压 |
| C7 | I/O输入输出 |



深圳市华德共创科技有限公司
Shenzhen Huade co-create Technology Co.,LTD
电话: 0755-27111216 传真: 0755-29940187

| -TOLERANCES- UNLESS OTHERWISE SPECIFIED 公差参数表 | | TITLE: MICRO SIM卡座PUSH 产品名称: 1.35H 带CD PIN | |
|---|------------|---|-----------------------------|
| X.X ±0.30 | X.X* ±3° | APPD: 核准: | PART NO: 产品编号: K-DYX-003 |
| X.XX ±0.20 | X.XX* ±2° | CHECK: 校对: 王建业 | DATE SCALE UNIT CODE NUMBER |
| X.XXX ±0.10 | X.XXX* ±1° | DRAW: 绘图: 黄艳兰 | 2016-03-12 1:1 mm A001 |